

Amendments to the Abstract:

Please replace the paragraph beginning on page 24 with the following:

~~In the present invention, a device Techniques for inspecting semiconductor devices. An inspection condition using chip matrix data and chip size data is set. [,] which inspects The intricate circuit patterns of at least one semiconductor device is inspected with the inspection condition. In an embodiment of the present invention, inspection uses using images formed by the irradiation of white light, a laser light, or an electron beam[,]. is equipped with a function that enables automatic setting of a plurality of parameters in the inspection device by using semiconductor device design data. Data obtained from the inspection is used to generate a revised inspection condition. Semiconductor devices are inspected using the revised inspection condition. This helps to improve the operation efficiency of inspection when the conditions required for inspection are set.~~